# 3 V LVDS Quad CMOS Differential Line Driver

**ANALOG DEVICES**

Data Sheet

## ADN4667

## FEATURES

±15 kV ESD protection on output pins
400 Mbps (200 MHz) switching rates
Flow through pinout simplifies PCB layout
300 ps typical differential skew
400 ps maximum differential skew
1.7 ns maximum propagation delay
3.3 V power supply
±310 mV differential signaling
Low power dissipation (10 mW typical)
Interoperable with existing 5 V LVDS receivers
High impedance on LVDS outputs on power-down
Conforms to TIA/EIA-644 LVDS standards
Industrial operating temperature range: −40°C to +85°C
Available in surface-mount (SOIC) and low profile
    TSSOP package
Qualified for automotive applications

## APPLICATIONS

Backplane data transmission
Cable data transmission
Clock distribution

## FUNCTIONAL BLOCK DIAGRAM



*Figure 1.*

## GENERAL DESCRIPTION

The ADN4667 is a quad, CMOS, low voltage differential signaling (LVDS) line driver offering data rates of over 400 Mbps (200 MHz) and ultralow power consumption. It features a flow through pinout for easy PCB layout and separation of input and output signals.

The device accepts low voltage TTL/CMOS logic signals and converts them to a differential current output of typically ±3.1 mA for driving a transmission medium such as a twisted pair cable. The transmitted signal develops a differential voltage of typically ±310 mV across a termination resistor at the receiving end. This is converted back to a TTL/CMOS logic level by an LVDS receiver, such as the ADN4668.
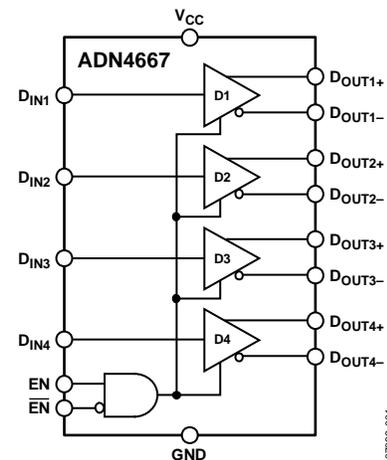
The ADN4667 also offers active high and active low enable/disable inputs (EN and $\overline{EN}$). These inputs control all four drivers and turn off the current outputs in the disabled state to reduce the quiescent power consumption to typically 10 mW.

The ADN4667 and its companion LVDS receiver, the ADN4668, offer a new solution to high speed, point-to-point data transmission, and a low power alternative to emitter-coupled logic (ECL) or positive emitter-coupled logic (PECL).

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# ADN4667* PRODUCT PAGE QUICK LINKS

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## DOCUMENTATION 🗗

**Application Notes**

- AN-1176: Component Footprints and Symbols in the Binary .Bxl File Format
- AN-1177: LVDS and M-LVDS Circuit Implementation Guide
- AN-1179: Junction Temperature Calculation for Analog Devices RS-485/RS-422, CAN, and LVDS/M-LVDS Transceivers

**Data Sheet**

- ADN4667: 3 V LVDS Quad CMOS Differential Line Driver Data Sheet

## TOOLS AND SIMULATIONS 🗗

- ADN4667 IBIS Model

## DESIGN RESOURCES 🗗

- ADN4667 Material Declaration
- PCN-PDN Information
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## REVISION HISTORY

# SPECIFICATIONS

$V_{CC}$ = 3.0 V to 3.6 V; $R_L$ = 100 Ω; $C_L$ = 15 pF to GND; all specifications $T_{MIN}$ to $T_{MAX}$, unless otherwise noted. All typical values are given for $V_{CC}$ = +3.3 V, $T_A$ = +25°C.

**Table 1.**

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions/Comments[1, 2] |
|---|---|---|---|---|---|---|
| LVDS OUTPUTS ($D_{OUT+}$, $D_{OUT−}$) | | | | | | |
| Differential Output Voltage | $V_{OD}$ | 250 | 310 | 450 | mV | See Figure 2 and Figure 4 |
| Change in Magnitude of $V_{OD}$ for Complementary Output States | $\Delta V_{OD}$ | | 1 | 35 | \|mV\| | See Figure 2 and Figure 4 |
| Offset Voltage | $V_{OS}$ | 1.125 | 1.17 | 1.375 | V | See Figure 2 and Figure 4 |
| Change in Magnitude of $V_{OS}$ for Complementary Output States | $\Delta V_{OS}$ | | 1 | 25 | \|mV\| | See Figure 2 and Figure 4 |
| Output High Voltage | $V_{OH}$ | | 1.33 | 1.6 | V | See Figure 2 and Figure 4 |
| Output Low Voltage | $V_{OL}$ | 0.90 | 1.02 | | V | See Figure 2 and Figure 4 |
| INPUTS ($D_{IN}$, EN, $\overline{EN}$) | | | | | | |
| Input High Voltage | $V_{IH}$ | 2.0 | | $V_{CC}$ | V | |
| Input Low Voltage | $V_{IL}$ | GND | | 0.8 | V | |
| Input High Current | $I_{IH}$ | −10 | +2 | +10 | µA | $V_{IN}$ = $V_{CC}$ or 2.5 V |
| Input Low Current | $I_{IL}$ | −10 | +2 | +10 | µA | $V_{IN}$ = GND or 0.4 V |
| Input Clamp Voltage | $V_{CL}$ | −1.5 | −0.8 | | V | $I_{CL}$ = −18 mA |
| LVDS OUTPUT PROTECTION ($D_{OUT+}$, $D_{OUT−}$) | | | | | | |
| Output Short-Circuit Current[3] | $I_{OS}$ | | −4.2 | −9.0 | mA | Enabled, $D_{IN}$ = $V_{CC}$, $D_{OUT+}$ = 0 V or $D_{IN}$ = GND, $D_{OUT−}$ = 0 V |
| Differential Output Short-Circuit Current[3] | $I_{OSD}$ | | −4.2 | −9.0 | mA | Enabled, $V_{OD}$ = 0 V |
| LVDS OUTPUT LEAKAGE ($D_{OUT+}$, $D_{OUT−}$) | | | | | | |
| Power-Off Leakage | $I_{OFF}$ | −20 | ±1 | +20 | µA | $V_{OUT}$ = 0 V or 3.6 V, $V_{CC}$ = 0 V or open |
| Output Three-State Current | $I_{OZ}$ | −10 | ±1 | +10 | µA | EN = 0.8 V and $\overline{EN}$ = 2.0 V, $V_{OUT}$ = 0 V or $V_{CC}$ |
| POWER SUPPLY | | | | | | |
| No Load Supply Current, Drivers Enabled | $I_{CC}$ | | 4.0 | 8.0 | mA | $D_{IN}$ = $V_{CC}$ or GND |
| Loaded Supply Current, Drivers Enabled | $I_{CCL}$ | | 20 | 30 | mA | $R_L$ = 100 Ω all channels, $D_{IN}$ = $V_{CC}$ or GND (all inputs) |
| No Load Supply Current, Drivers Disabled | $I_{CCZ}$ | | 2.2 | 6.0 | mA | $D_{IN}$ = $V_{CC}$ or GND, EN = GND, $\overline{EN}$ = $V_{CC}$ |
| ESD PROTECTION | | | | | | |
| $D_{OUT+}$, $D_{OUT−}$ | | | ±15 | | kV | Human body model |
| All Pins Except $D_{OUT+}$, $D_{OUT−}$ | | | ±4 | | kV | Human body model |

[1] Current into device pins is defined as positive. Current out of device pins is defined as negative. All voltages are referenced to ground except $V_{OD}$, $\Delta V_{OD}$, and $\Delta V_{OS}$.
[2] The ADN4667 is a current mode device and functions within data sheet specifications only when a resistive load is applied to the driver outputs. Typical range is 90 Ω to 110 Ω.
[3] Output short-circuit current ($I_{OS}$) is specified as magnitude only; minus sign indicates direction only.

## AC CHARACTERISTICS

$V_{CC}$ = 3.0 V to 3.6 V; $R_L$ = 100 Ω; $C_L$[1] = 15 pF to GND; all specifications $T_{MIN}$ to $T_{MAX}$, unless otherwise noted. All typical values are given for $V_{CC}$ = +3.3 V, $T_A$ = +25°C.

**Table 2.**

| Parameter[2] | Min | Typ | Max | Unit | Conditions/Comments[3, 4] |
|---|---|---|---|---|---|
| Differential Propagation Delay, High to Low, $t_{PHLD}$ | 0.5 | 0.9 | 1.7 | ns | See Figure 3 and Figure 4 |
| Differential Propagation Delay, Low to High, $t_{PLHD}$ | 0.5 | 1.2 | 1.7 | ns | See Figure 3 and Figure 4 |
| Differential Pulse Skew $|t_{PHLD} - t_{PLHD}|$, $t_{SKD1}$[5] | 0 | 0.3 | 0.4 | ns | See Figure 3 and Figure 4 |
| Channel-to-Channel Skew, $t_{SKD2}$[6] | 0 | 0.4 | 0.5 | ns | See Figure 3 and Figure 4 |
| Differential Part-to-Part Skew, $t_{SKD3}$[7] | 0 | | 1.0 | ns | See Figure 3 and Figure 4 |
| Differential Part-to-Part Skew, $t_{SKD4}$[8] | 0 | | 1.2 | ns | See Figure 3 and Figure 4 |
| Rise Time, $t_r$ | | 0.5 | 1.5 | ns | See Figure 3 and Figure 4 |
| Fall Time, $t_f$ | | 0.5 | 1.5 | ns | See Figure 3 and Figure 4 |
| Disable Time High to Inactive, $t_{PHZ}$ | | 2 | 5 | ns | See Figure 5 and Figure 6 |
| Disable Time Low to Inactive, $t_{PLZ}$ | | 2 | 5 | ns | See Figure 5 and Figure 6 |
| Enable Time Inactive to High, $t_{PZH}$ | | 3 | 7 | ns | See Figure 5 and Figure 6 |
| Enable Time Inactive to Low, $t_{PZL}$ | | 3 | 7 | ns | See Figure 5 and Figure 6 |
| Maximum Operating Frequency, $f_{MAX}$[9] | 200 | 250 | | MHz | See Figure 5 and Figure 6 |

[1] $C_L$ includes probe and jig capacitance.
[2] AC parameters are guaranteed by design and characterization.
[3] Generator waveform for all tests unless otherwise specified: f = 50 MHz, $Z_O$ = 50 Ω, $t_r$ ≤ 1 ns, and $t_f$ ≤ 1 ns.
[4] All input voltages are for one channel unless otherwise specified. Other inputs are set to GND.
[5] $t_{SKD1}$ = $|t_{PHLD} - t_{PLHD}|$ is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.
[6] $t_{SKD2}$ is the differential channel-to-channel skew of any event on the same device.
[7] $t_{SKD3}$, differential part-to-part skew, is defined as the difference between the minimum and maximum specified differential propagation delays. This specification applies to devices at the same $V_{CC}$ and within 5°C of each other within the operating temperature range.
[8] $t_{SKD4}$, part-to-part skew, is the differential channel-to-channel skew of any event between devices. This specification applies to devices over recommended operating temperatures and voltage ranges, and across process distribution. $t_{SKD4}$ is defined as |maximum − minimum| differential propagation delay.
[9] $f_{MAX}$ generator input conditions: $t_r$ = $t_f$ < 1 ns (0% to 100%), 50% duty cycle, 0 V to 3 V. Output criteria: duty cycle = 45% to 55%, $V_{OD}$ > 250 mV, all channels switching.
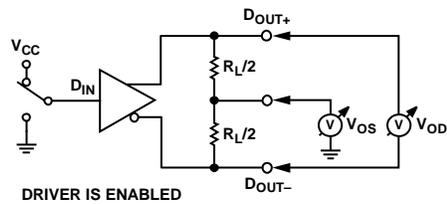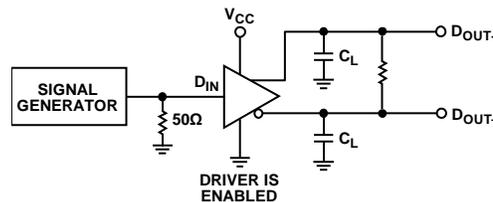
### Test Circuits and Timing Diagrams



Figure 2. Test Circuit for Driver $V_{OD}$ and $V_{OS}$



NOTES
1. $C_L$ INCLUDES LOAD AND TEST JIG CAPACITANCE.

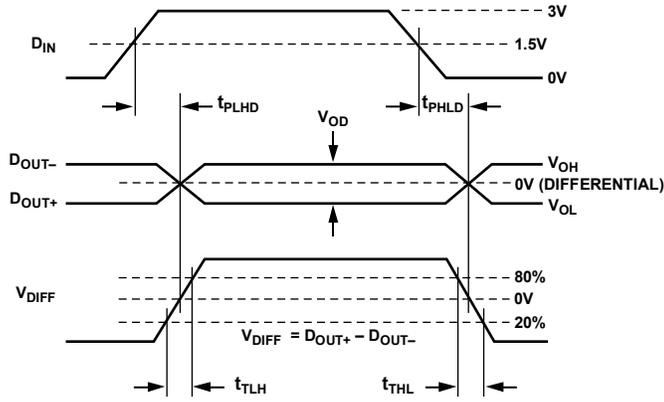Figure 3. Test Circuit for Driver Propagation Delay and Transition Time

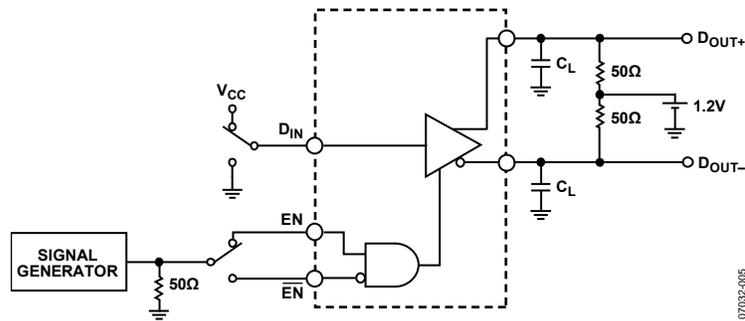*Figure 4. Driver Propagation Delay and Transition Time Waveforms*
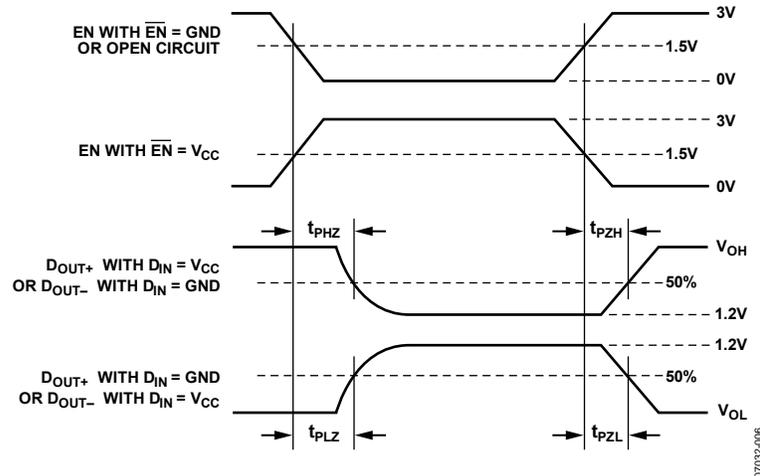


*Figure 5. Test Circuit for Driver Three-State Delay*



*Figure 6. Driver Three-State Delay Waveforms*

# ABSOLUTE MAXIMUM RATINGS

$T_A$ = 25°C, unless otherwise noted.

**Table 3.**

| Parameter | Rating |
|---|---|
| $V_{CC}$ to GND | −0.3 V to +4 V |
| Input Voltage ($D_{IN}$) to GND | −0.3 V to $V_{CC}$ + 0.3 V |
| Enable Input Voltage (EN, $\overline{EN}$) to GND | −0.3 V to $V_{CC}$ + 0.3 V |
| Output Voltage ($D_{OUT+}$, $D_{OUT−}$) to GND | −0.3 V to $V_{CC}$ + 0.3 V |
| Short-Circuit Duration ($D_{OUT+}$, $D_{OUT−}$) to GND | Continuous |
| Industrial Operating Temperature Range | −40°C to +85°C |
| Storage Temperature Range | −65°C to +150°C |
| Junction Temperature ($T_J$ max) | 150°C |
| Power Dissipation | ($T_J$ max − $T_A$)/$\theta_{JA}$ |
| $\theta_{JA}$ Thermal Impedance | |
|    TSSOP Package | 150.4°C/W |
|    SOIC Package | 125°C/W |
| Reflow Soldering Peak Temperature (10sec) | 260°C max |

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## ESD CAUTION

**ESD (electrostatic discharge) sensitive device.** Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.
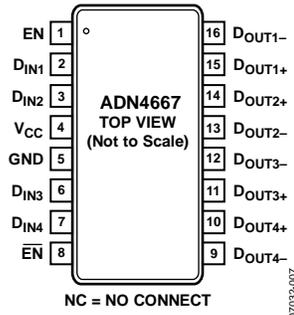
# PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



Figure 7. Pin Configuration

**Table 4. Pin Function Descriptions**

| Pin No. | Mnemonic | Description |
|---|---|---|
| 1 | EN | Active High Enable and Power-Down Input (3 V TTL/CMOS). If $\overline{EN}$ is held low or open circuit, EN enables the drivers when high and disables the drivers when low. |
| 2 | $D_{IN1}$ | Driver Channel 1 Logic Input. |
| 3 | $D_{IN2}$ | Driver Channel 2 Logic Input. |
| 4 | $V_{CC}$ | Power Supply Input. These parts can be operated from 3.0 V to 3.6 V. The supply should be decoupled with a 10 μF solid tantalum capacitor in parallel with a 0.1 μF capacitor to GND. |
| 5 | GND | Ground Reference Point for All Circuitry on the Part. |
| 6 | $D_{IN3}$ | Driver Channel 3 Logic Input. |
| 7 | $D_{IN4}$ | Driver Channel 4 Logic Input. |
| 8 | $\overline{EN}$ | Active Low Enable and Power-Down Input with Pull-Down (3 V TTL/CMOS). If EN is held high, $\overline{EN}$ enables the drivers when low or open circuit and disables the drivers and powers down the device when high. |
| 9 | $D_{OUT4-}$ | Channel 4 Inverting Output Current Driver. When $D_{IN4}$ is high, current flows into $D_{OUT4-}$. When $D_{IN4}$ is low, current flows out of $D_{OUT4-}$. |
| 10 | $D_{OUT4+}$ | Channel 4 Noninverting Output Current Driver. When $D_{IN4}$ is high, current flows out of $D_{OUT4+}$. When $D_{IN4}$ is low, current flows into $D_{OUT4+}$. |
| 11 | $D_{OUT3+}$ | Channel 3 Noninverting Output Current Driver. When $D_{IN3}$ is high, current flows out of $D_{OUT3+}$. When $D_{IN3}$ is low, current flows into $D_{OUT3+}$. |
| 12 | $D_{OUT3-}$ | Channel 3 Inverting Output Current Driver. When $D_{IN3}$ is high, current flows into $D_{OUT3-}$.When $D_{IN3}$ is low, current flows out of $D_{OUT3-}$. |
| 13 | $D_{OUT2-}$ | Channel 2 Inverting Output Current Driver. When $D_{IN2}$ is high, current flows into $D_{OUT2-}$. When $D_{IN2}$ is low, current flows out of $D_{OUT2-}$. |
| 14 | $D_{OUT2+}$ | Channel 2 Noninverting Output Current Driver. When $D_{IN2}$ is high, current flows out of $D_{OUT2+}$. When $D_{IN2}$ is low, current flows into $D_{OUT2+}$. |
| 15 | $D_{OUT1+}$ | Channel 1 Noninverting Output Current Driver. When $D_{IN1}$ is high, current flows out of $D_{OUT1+}$. When $D_{IN1}$ is low, current flows into $D_{OUT1+}$. |
| 16 | $D_{OUT1-}$ | Channel 1 Inverting Output Current Driver. When $D_{IN1}$ is high, current flows into $D_{OUT1-}$. When $D_{IN1}$ is low, current flows out of $D_{OUT1-}$. |

# TYPICAL PERFORMANCE CHARACTERISTICS
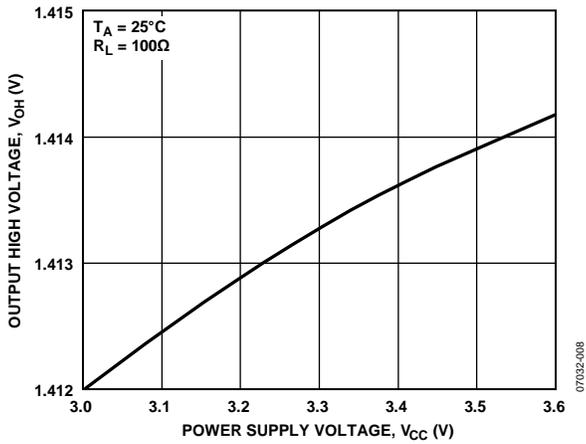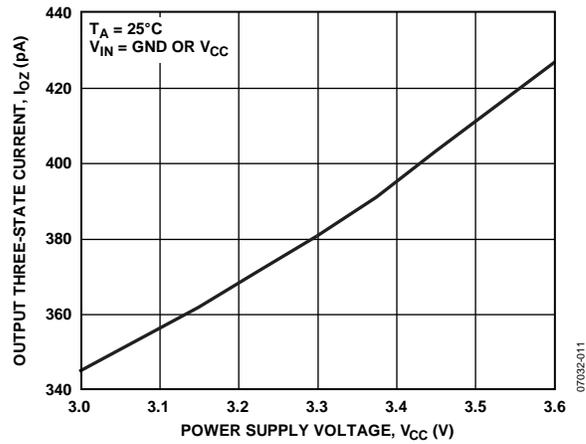


Figure 8. Output High Voltage vs. Power Supply Voltage
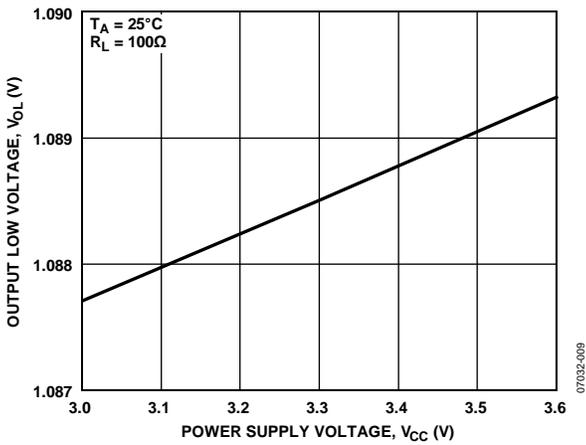


Figure 9. Output Low Voltage vs. Power Supply Voltage



Figure 10. Output Short-Circuit Current vs. Power Supply Voltage



Figure 11. Output Three-State Current vs. Power Supply Voltage



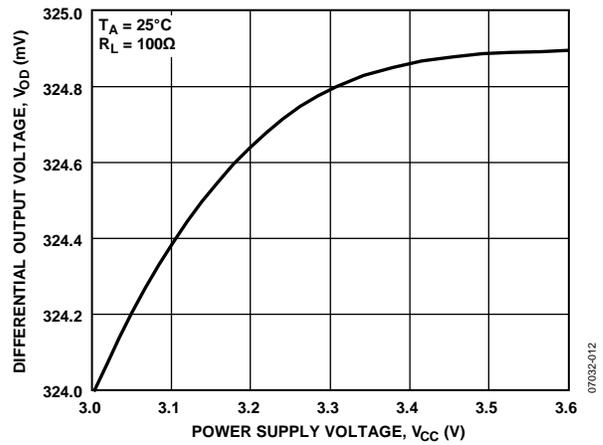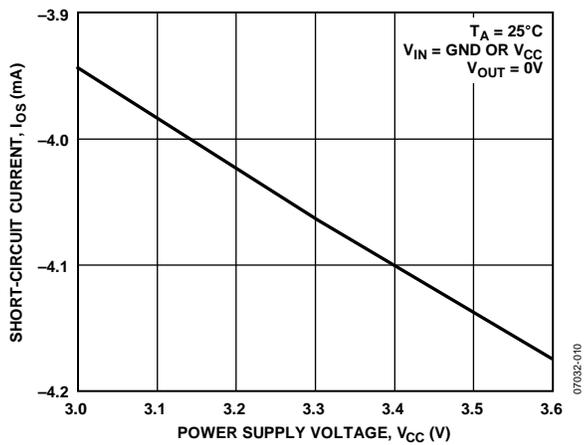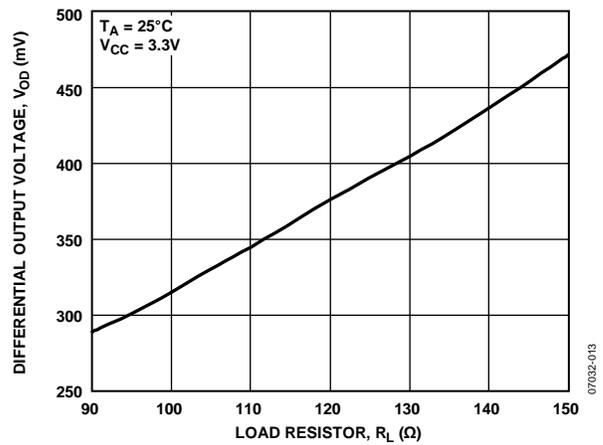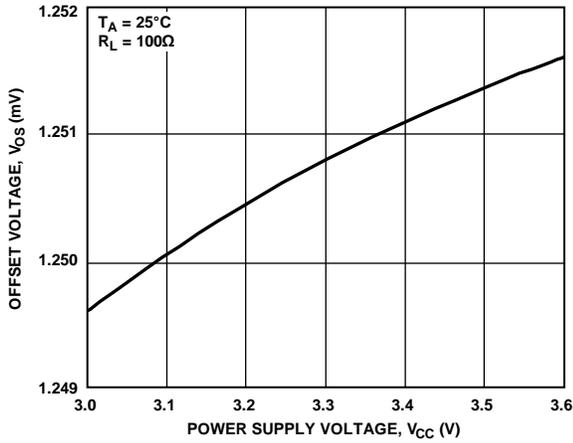Figure 12. Differential Output Voltage vs. Power Supply Voltage



Figure 13. Differential Output Voltage vs. Load Resistor
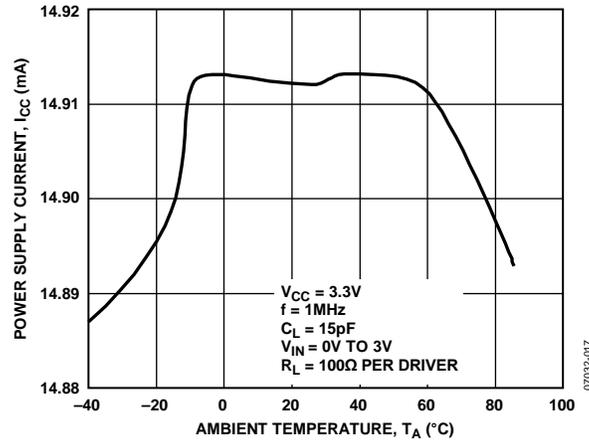
Figure 14. Offset Voltage vs. Power Supply Voltage
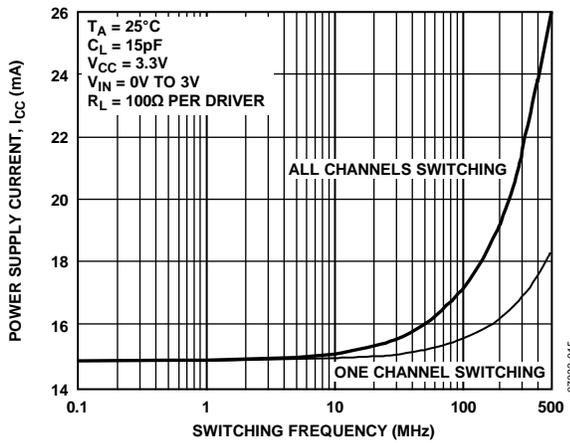


Figure 15.Power Supply Current vs. Switching Frequency



Figure 16. Power Supply Current vs. Power Supply Voltage



Figure 17. Power Supply Current vs. Ambient Temperature



Figure 18. Differential Propagation Delay vs. Power Supply Voltage
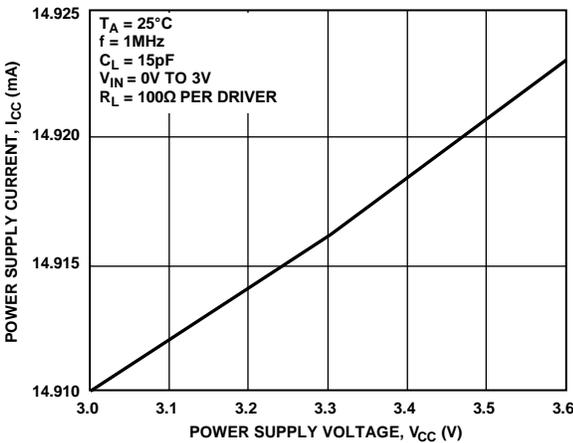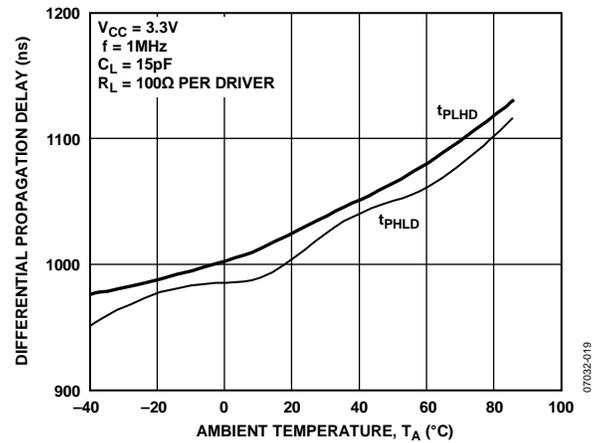


Figure 19. Differential Propagation Delay vs. Ambient Temperature
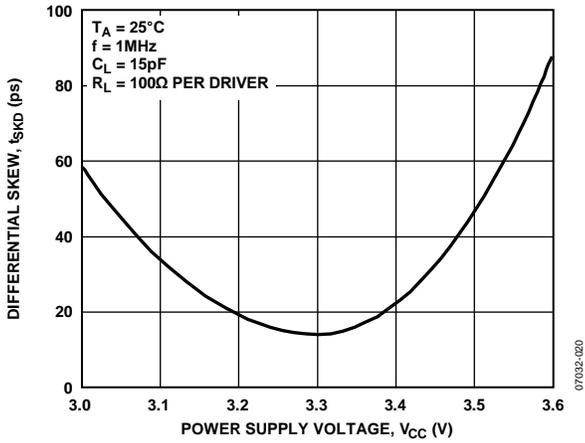
*Figure 20. Differential Skew vs. Supply Voltage*
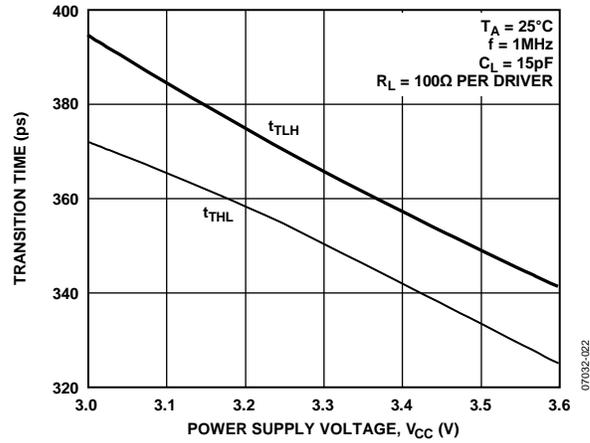


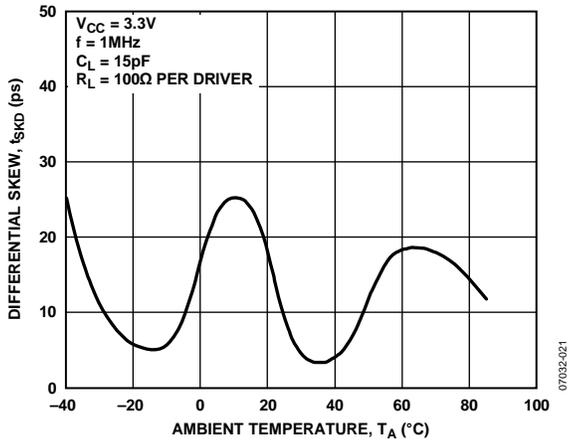*Figure 22. Transition Time vs. Supply Voltage*
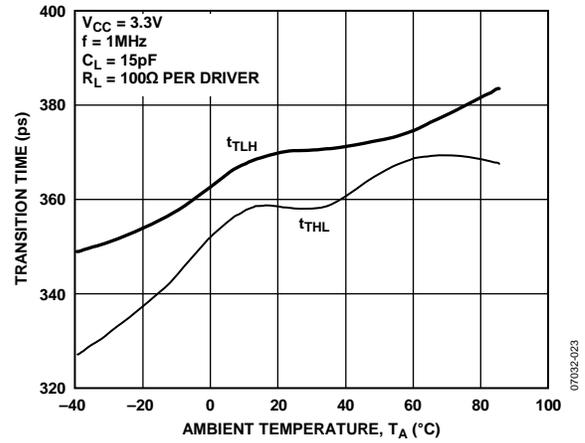


*Figure 21. Differential Skew vs. Ambient Temperature*



*Figure 23. Transition Time vs. Ambient Temperature*

# THEORY OF OPERATION

The ADN4667 is a quad line driver for low voltage differential signaling. It takes a single-ended 3 V logic signal and converts it to a differential current output. The data can then be transmitted for considerable distances, over media such as a twisted pair cable or PCB backplane, to an LVDS receiver like the ADN4668, where it develops a voltage across a terminating resistor, $R_T$. This resistor is chosen to match the characteristic impedance of the medium, typically around 100 Ω. The differential voltage is detected by the receiver and converted back into a single-ended logic signal.

When $D_{IN}$ is high (Logic 1), current flows out of the $D_{OUT+}$ pin (current source) through $R_T$ and back into the $D_{OUT-}$ pin (current sink). At the receiver, this current develops a positive differential voltage across $R_T$ (with respect to the inverting input) and gives a Logic 1 at the receiver output. When $D_{IN}$ is low, $D_{OUT+}$ sinks current and $D_{OUT-}$ sources current; a negative differential voltage across $R_T$ gives a Logic 0 at the receiver output.

The output drive current is between ±2.5 mA and ±4.5 mA (typically ±3.1 mA), developing between ±250 mV and ±450 mV across a 100 Ω termination resistor. The received voltage is centered around the receiver offset of 1.2 V. Therefore, the noninverting receiver input is typically (1.2 V + [310 mV/2]) = 1.355 V, and the inverting receiver input is (1.2 V − [310 mV/2]) = 1.045 V for Logic 1. For Logic 0, the inverting and noninverting output voltages are reversed. Note that because the differential voltage reverses polarity, the peak-to-peak voltage swing across $R_T$ is twice the differential voltage.

Current mode drivers offer considerable advantages over voltage mode drivers such as RS-422 drivers. The operating current remains fairly constant with increased switching frequency, whereas that of voltage mode drivers increase exponentially in most cases. This is caused by the overlap as internal gates switch between high and low, which causes

currents to flow from the device power supply to ground. A current mode device simply reverses a constant current between its two outputs, with no significant overlap currents.

This is similar to emitter-coupled logic (ECL) and positive emitter-coupled logic (PECL), but without the high quiescent current of ECL and PECL.

## ENABLE INPUTS

The active high and active low enable inputs deactivate all the current drivers when in the disabled state. This also powers down the device and reduces the current consumption from typically 20 mA to typically 2.2 mA. A truth table for the enable inputs is shown in Table 5.

**Table 5. Enable Inputs Truth Table**

| EN | $\overline{EN}$ | $D_{IN}$ | $D_{OUT+}$ | $D_{OUT-}$ |
|---|---|---|---|---|
| H | L or open | L | $I_{SINK}$ | $I_{SOURCE}$ |
| H | L or open | H | $I_{SOURCE}$ | $I_{SINK}$ |
| Any other combination of EN and $\overline{EN}$ | | X | Inactive | Inactive |

## APPLICATIONS INFORMATION

Figure 24 shows a typical application for point-to-point data transmission using the ADN4667 as the driver and the ADN4668 as the receiver.
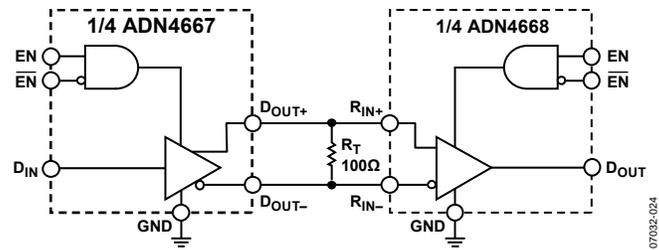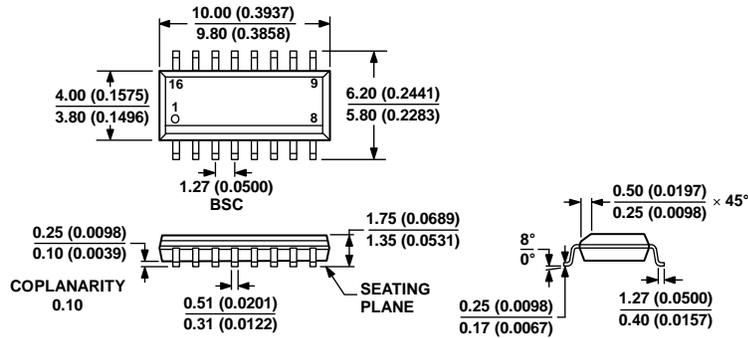


Figure 24. Typical Application Circuit
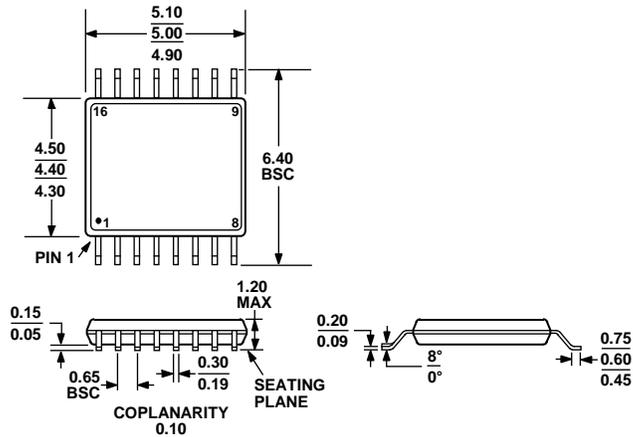
## OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-012-AC

CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

*Figure 25. 16-Lead Standard Small Outline Package [SOIC_N]*
*Narrow Body*
*(R-16)*
*Dimensions shown in millimeters and (inches)*



COMPLIANT TO JEDEC STANDARDS MO-153-AB

*Figure 26. 16-Lead Thin Shrink Small Outline Package [TSSOP]*
*(RU-16)*
*Dimensions shown in millimeters*

## ORDERING GUIDE

| Model[1, 2] | Temperature Range | Package Description | Package Option |
|---|---|---|---|
| ADN4667ARZ | −40°C to +85°C | 16-Lead Standard Small Outline Package [SOIC_N] | R-16 |
| ADN4667ARZ-REEL7 | −40°C to +85°C | 16-Lead Standard Small Outline Package [SOIC_N] | R-16 |
| ADN4667ARUZ | −40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADN4667ARUZ-REEL7 | −40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADN4667WARZ-REEL7 | −40°C to +85°C | 16-Lead Standard Small Outline Package [SOIC_N] | R-16 |

[1] Z = RoHS Compliant Part.

[2] W = Qualified for Automotive Applications

## AUTOMOTIVE PRODUCTS

The ADN4667W model is available with controlled manufacturing to support the quality and reliability requirements of automotive applications. Note that this automotive model may have specifications that differ from the commercial models; therefore, designers should review the Specifications section of this data sheet carefully. Only the automotive grade product shown is available for use in automotive applications. Contact your local Analog Devices account representative for specific product ordering information and to obtain the specific Automotive Reliability reports for this model.

## NOTES

## NOTES

# NOTES

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